

(1,27mm) .050"
TFM, TFML SERIES





SMT HIGH RELIABILITY HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?TFM or www.samtec.com?TFML

Insulator Material: Black Liquid Crystal Polymer Terminal Material: Phosphor Bronze Plating:

Plating: Au or Sn over 50μ" (1,27μm) Ni Voltage Rating: 350 VAC mated with SFM Operating Temp Range: -55°C to +125°C

(1)

RoHS Compliant:

CURRENT RATING	
AMBIENT TEMP	TFM/SFM
20°C	5A
40°C	4.5A
60°C	3.9A
95°C	2.6A

6 POSITIONS (2x3) POWERED

Processing: Lead-Free Solderable:

Yes

SMT Lead Coplanarity: (0,10mm) .004" max (05-25) (0,15mm) .006" max (30-50)

APPLICATION SPECIFIC OPTION

Solder nail option for (2,36mm) .093" thick board available. Call Samtec.

Note: Other Gold plating options available. Contact Samtec.

Note:

Some sizes, styles and options are non-standard, non-returnable.

TFM Mates with: SFM, SFMC, SFSD

TFML
Mates with:
SFML, SFSD
(-XL option),
SFSDT
(-XL option)

MATED HEIGHT		
LEAD STYLE		MATED
TFM	SFM	HEIGHT*
-02	-02	(6,35) .250
-12		(8,13) .320
-22		(9,91) .390
-32		(11,81) .465
*Processing conditions will affect mated height.		

 1,27mm SFM/TFM
 Rated @ 3dB Insertion Loss

 6,35mm Stack Height
 6.0 GHz / 12 Gbps

 Single-Ended Signaling
 6.0 GHz / 14 Gbps

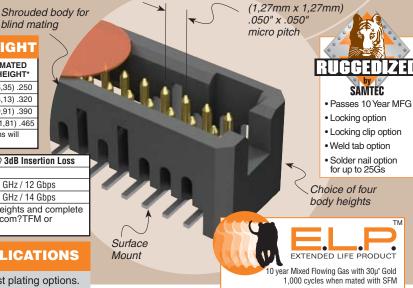
 Differential Pair Signaling
 7.0 GHz / 14 Gbps

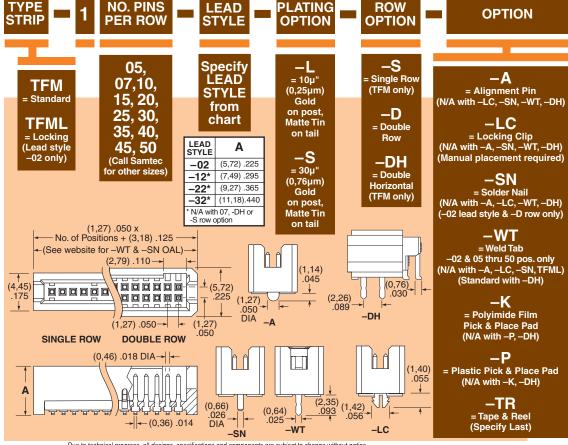
 Performance data for other stack heights and complete

Performance data for other stack heights and complete test data available at www.samtec.com?TFM or contact sig@samtec.com

COST-SAVING APPLICATIONS

See TFC Series for lower cost plating options.





Due to technical progress, all designs, specifications and components are subject to change without notice.

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